



PART NO. : TG10-DA1NSLF

6PIN SMT ISOLATION MODULE
 DESIGNED FOR CIRRUS LOGIC DIGITAL AUDIO
 INTERFACE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
 CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @25°C

TURNS RATIO

P1-2:P6-5 1:1 ±2%

OCL (100kHz,0.1V)

P1-2 750µH nom

DCR P1-2

0.5Ω max

LL P1-2

1.0µH max

Cw/w P1-6

18pF max

(Ground P3)

9pF max

BANDWIDTH (Nominal)

10kHz-200MHz

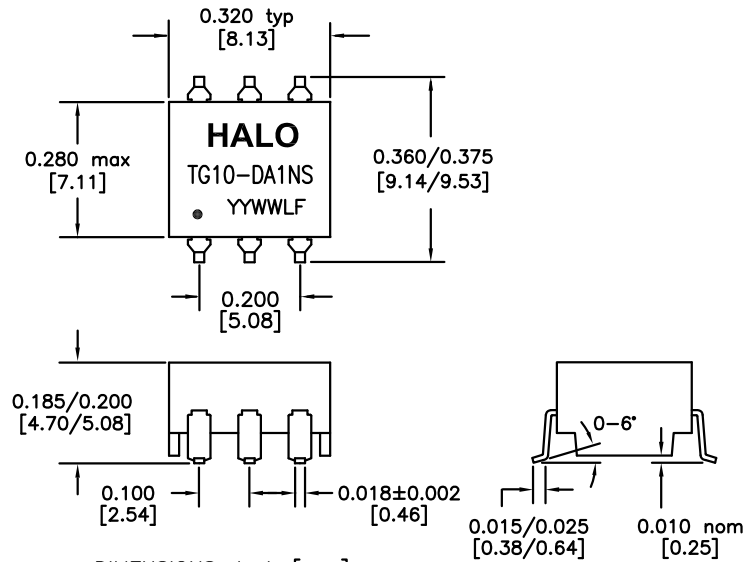
ISOLATION

PRI - SEC

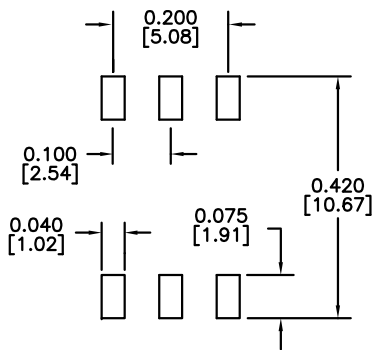
1500Vrms

PRI,SEC - SHIELD

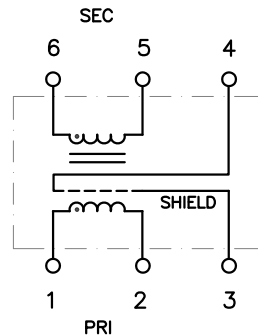
1500Vrms



DIMENSIONS: Inch [mm]
 CO-PLANARITY: 0.004 [0.10]
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS



ONLY ONE END OF THE SHIELD CAN BE GROUNDED

HALO/PBL

CALIFORNIA, USA
 KOWLOON, HONG KONG
 SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	CIRRUS LOGIC DIGITAL AUDIO		DRAWN	LI ZHI ZHONG	5/4/16	A	PROD. RELEASE
PART NO.	TG10-DA1NSLF		CHECKED	LEI KEONG	8/8/16	B	ADD BW SPEC.
SCALE	NONE	PAGE	APPROVED	PETER LU	8/8/16	C	UPDATE
		1 OF 1	FILE	DA1NSLF.DWG		D	UPDATE DESC.

